# RAK3272S Breakout Board

Thank you for choosing **RAK3272S Breakout Board** in your awesome IoT Project! 🎉 To help you get started, we have provided you all the necessary documentation for your product.

- Quick Start Guide
- AT Command Manual
- AT Command Migration Guide of RAK3172 to RUI3 ⬈
- Datasheet

## Product Description

RAK3272S Breakout Board is specifically designed to allow easy access to the pins on the board in order to simplify development and testing. The breakout board footprint is based on the XBee form factor, and its main purpose is to allow the RAK3172 stamp module pins to be transferred to 2.54 mm headers.

The board itself has the RAK3172 at its core, integrating a STM32WLE5CC chip. It has Ultra-Low Power Consumption of 1.69 uA in sleep mode.

This module complies with Class A, B, & C of LoRaWAN 1.0.3 specifications. It also supports LoRa Point-to-Point (P2P) communication mode, which helps you in implementing your own customized long-range LoRa network quickly.

## Product Features

- Based on RAK3172
- Custom firmware using Arduino via RUI3 API
- I/O ports: UART/I2C/GPIO/SPI
- Serial Wire Debug (SWD) interface
- Module size: 25.4 x 32.3 mm
- Supply Voltage: 2.0 V ~ 3.6 V
- Temperature Range: -40 °C ~ 85 °C

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